



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC032NE2LS		<b>Issued</b>		26. September 2017		
<b>MA#</b>		MA001015222						
<b>Package</b>		PG-TDSON-8-6		<b>Weight*</b>		118.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.24	0.24	2411	2411
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		320	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	32.00	32.04	319969	320385
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	394	394
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		748	
	plastics	epoxy resin	-	6.268	5.31		53109	
	inorganic material	silicondioxide	60676-86-0	37.783	32.02	37.40	320150	374007
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12300	12300
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1403	1403
solder	noble metal	silver	7440-22-4	0.012	0.01		98	
	non noble metal	tin	7440-31-5	0.009	0.01		79	
	non noble metal	lead	7439-92-1	0.442	0.37	0.39	3748	3925
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.59	9.60	95919	96044
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.89	18.92	188885	189131
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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